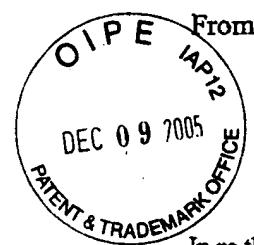


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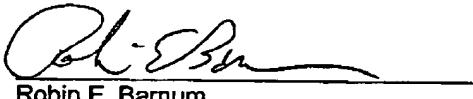
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Duy Q. Nguyen, et al. TI-30110
 Serial No.: 10/007,840 Art Unit: 2664
 Filed: October 30, 2001 Examiner: Jamal A. Fox
 For: External Bus Arbitration Technique for Multicore DSP Device Conf. No.: 7621

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